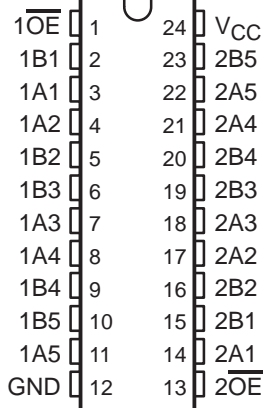


# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

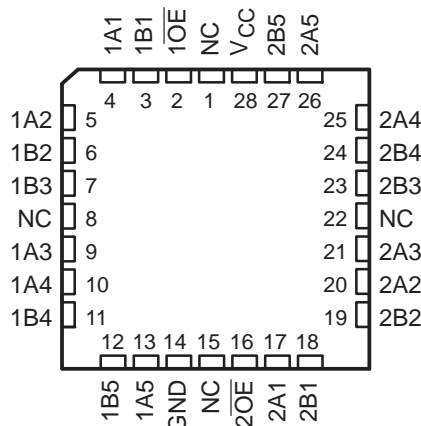
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

SN54CBTD3384 . . . JT OR W PACKAGE  
SN74CBTD3384 . . . DB, DBQ, DGV, DW, OR PW PACKAGE  
(TOP VIEW)



- Designed to Be Used in Level-Shifting Applications

SN54CBTD3384 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'CBTD3384 devices provide ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switches allows connections to be made without adding propagation delay. A diode to  $V_{CC}$  is integrated on the die to allow for level shifting from 5-V signals at the device inputs to 3.3-V signals at the device outputs.

These devices are organized as two 5-bit switches with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the switch is on, and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the two ports.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – DW	Tube	SN74CBTD3384DW	CBTD3384
		Tape and reel	SN74CBTD3384DWR	
	SSOP – DB	Tape and reel	SN74CBTD3384DBR	CC384
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBTD3384DBQR	CBTD3384
	TSSOP – PW	Tube	SN74CBTD3384PW	CC384
		Tape and reel	SN74CBTD3384PWR	
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74CBTD3384DGVR	CC384
	CDIP – JT	Tube	SNJ54CBTD3384JT	SNJ54CBTD3384JT
	CFP – W	Tube	SNJ54CBTD3384W	SNJ54CBTD3384W
	LCCC – FK	Tube	SNJ54CBTD3384FK	SNJ54CBTD3384FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

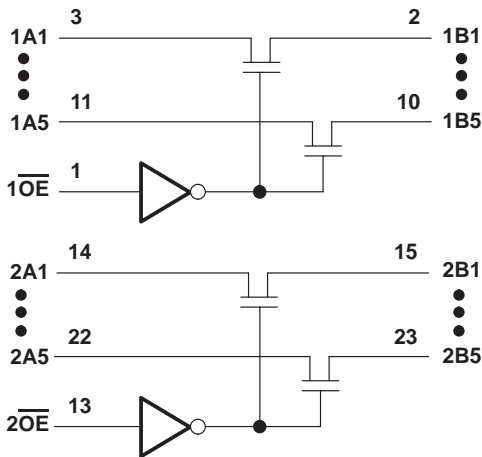
# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

FUNCTION TABLE  
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
1OE	2OE	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

## logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, JT, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_{IK}$ ( $V_{I/O} < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	63°C/W
DBQ package	61°C/W
DGV package	86°C/W
DW package	46°C/W
PW package	88°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

## recommended operating conditions (see Note 3)

		SN54CBTD3384		SN74CBTD3384		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level control input voltage	2		2		V
$V_{IL}$	Low-level control input voltage		0.8		0.8	V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

In applications with fast edge rates, multiple outputs switching, and operating at high frequencies, the output may have little or no level-shifting effect.

NOTE 3: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54CBTD3384			SN74CBTD3384			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2			-1.2	V
$V_{OH}$		See Figure 2							
$I_I$		$V_{CC} = 5.5\text{ V}$ , $V_I = 5.5\text{ V}$ or GND			$\pm 1$			$\pm 1$	$\mu\text{A}$
$I_{CC}$		$V_{CC} = 5.5\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND			1.5			1.5	mA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND			2.5			2.5	mA
$C_i$	Control inputs	$V_I = 3\text{ V}$ or 0			3			3	pF
$C_{iO}(\text{OFF})$		$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$			3.5			3.5	pF
$r_{on}^\S$		$V_{CC} = 4.5\text{ V}$ , $V_I = 0$ , $I_I = 64\text{ mA}$			5			5	$\Omega$
		$V_{CC} = 4.5\text{ V}$ , $V_I = 0$ , $I_I = 30\text{ mA}$			5			5	
		$V_{CC} = 4.5\text{ V}$ , $V_I = 2.4\text{ V}$ , $I_I = 15\text{ mA}$			35			35	

† Typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBTD3384		SN74CBTD3384		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\P$	A or B	B or A		0.25		0.25	ns
$t_{en}$	$\overline{OE}$	A or B	2.2	9.7	2.3	7	ns
$t_{dis}$	$\overline{OE}$	A or B	1.5	8.6	1.7	5.3	ns

¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

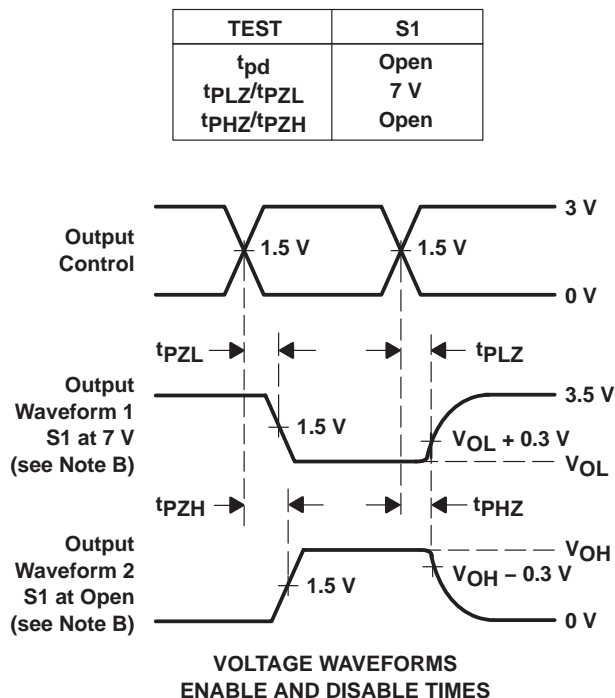
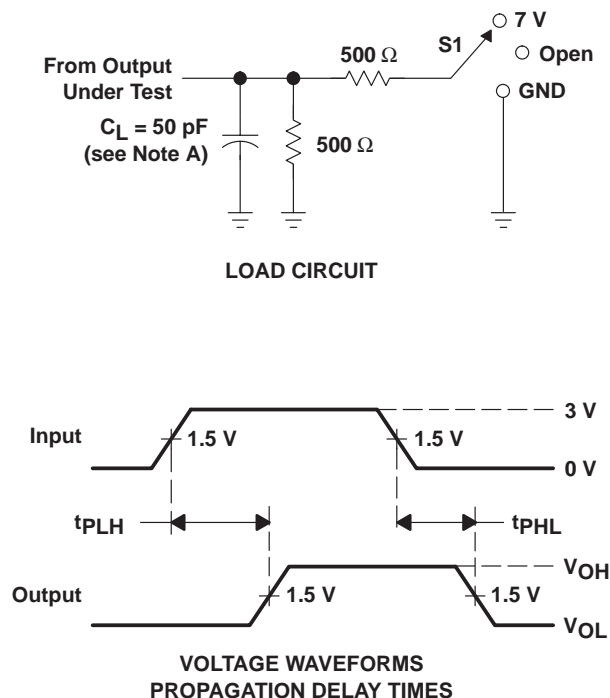
# SN54CBTD3384, SN74CBTD3384

## 10-BIT FET BUS SWITCHES

### WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

#### PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

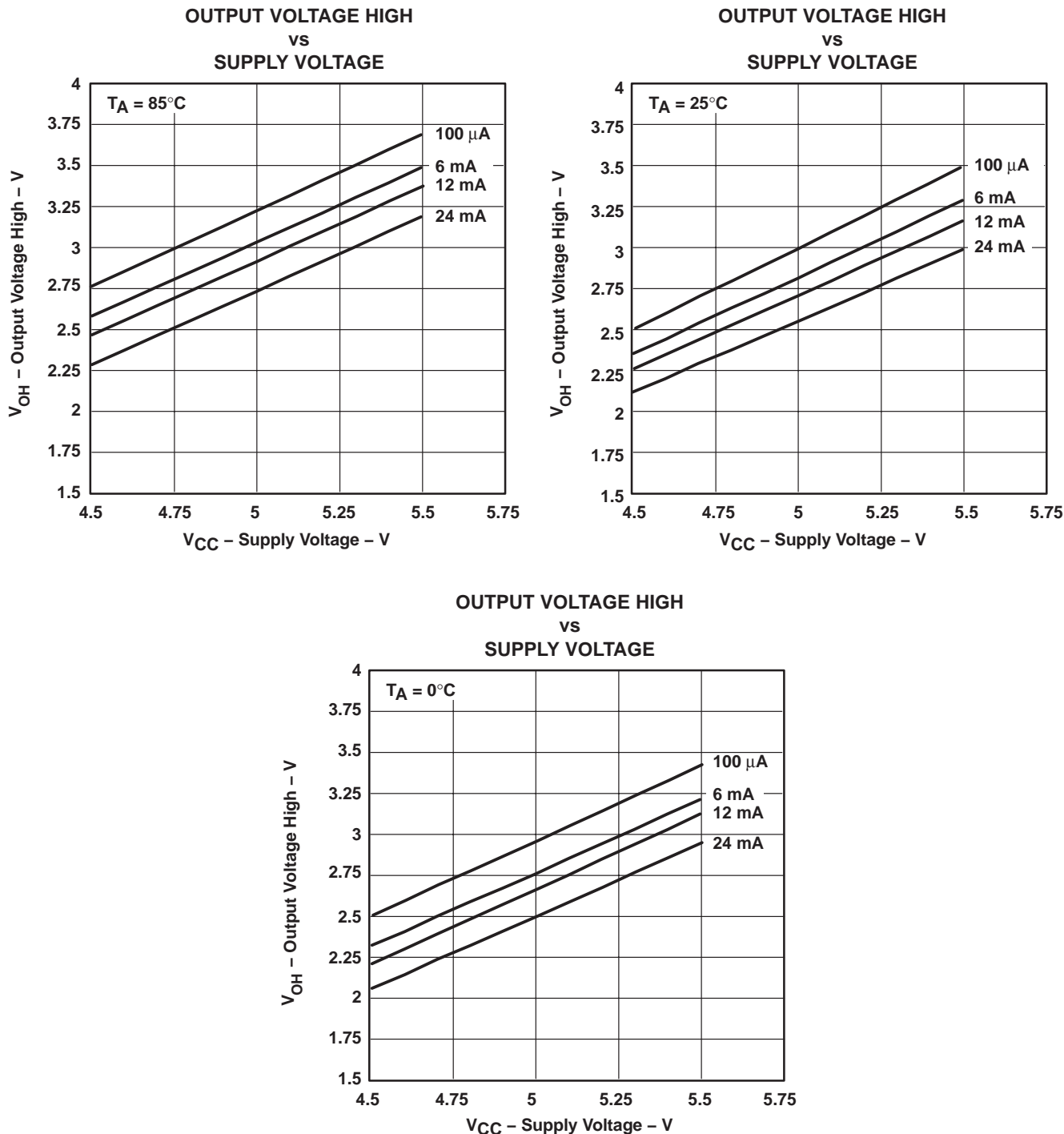


Figure 2. VOH Values

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9752701Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9752701QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-9752701QLA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
74CBTD3384DBQRE4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
74CBTD3384DBQRG4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
74CBTD3384DGVRE4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTD3384DGVRG4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74CBTD3384DBQR	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74CBTD3384DBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DGVR	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI
SN74CBTD3384PWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD3384PWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54CBTD3384FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54CBTD3384JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SNJ54CBTD3384W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTD3384DBQR	SSOP/QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CBTD3384DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74CBTD3384DGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CBTD3384DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74CBTD3384PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1



## TAPE AND REEL BOX DIMENSIONS



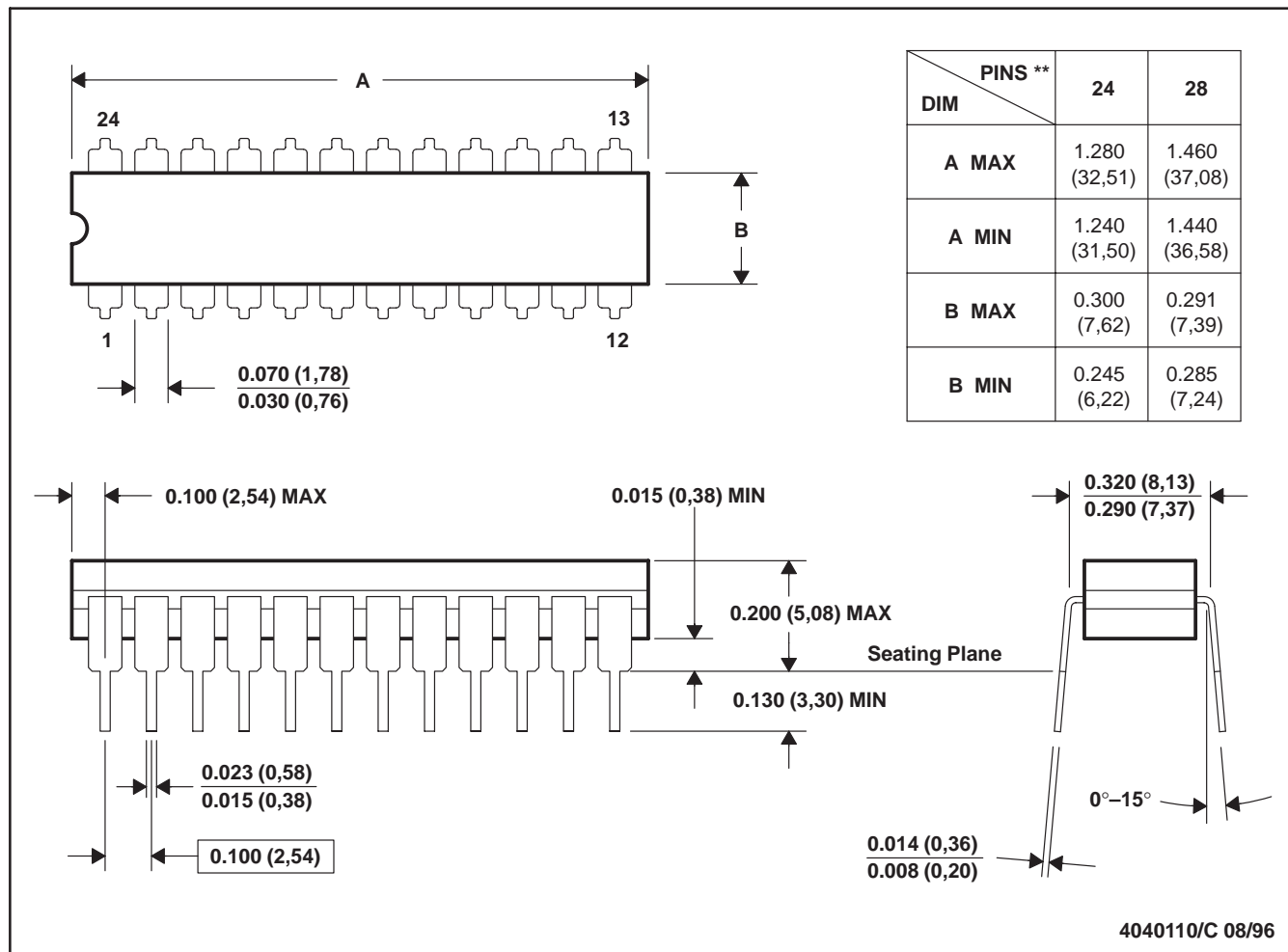
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTD3384DBQR	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0
SN74CBTD3384DBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74CBTD3384DGVR	TVSOP	DGV	24	2000	346.0	346.0	29.0
SN74CBTD3384DWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74CBTD3384PWR	TSSOP	PW	24	2000	346.0	346.0	33.0

## JT (R-GDIP-T\*\*)

24 LEADS SHOWN

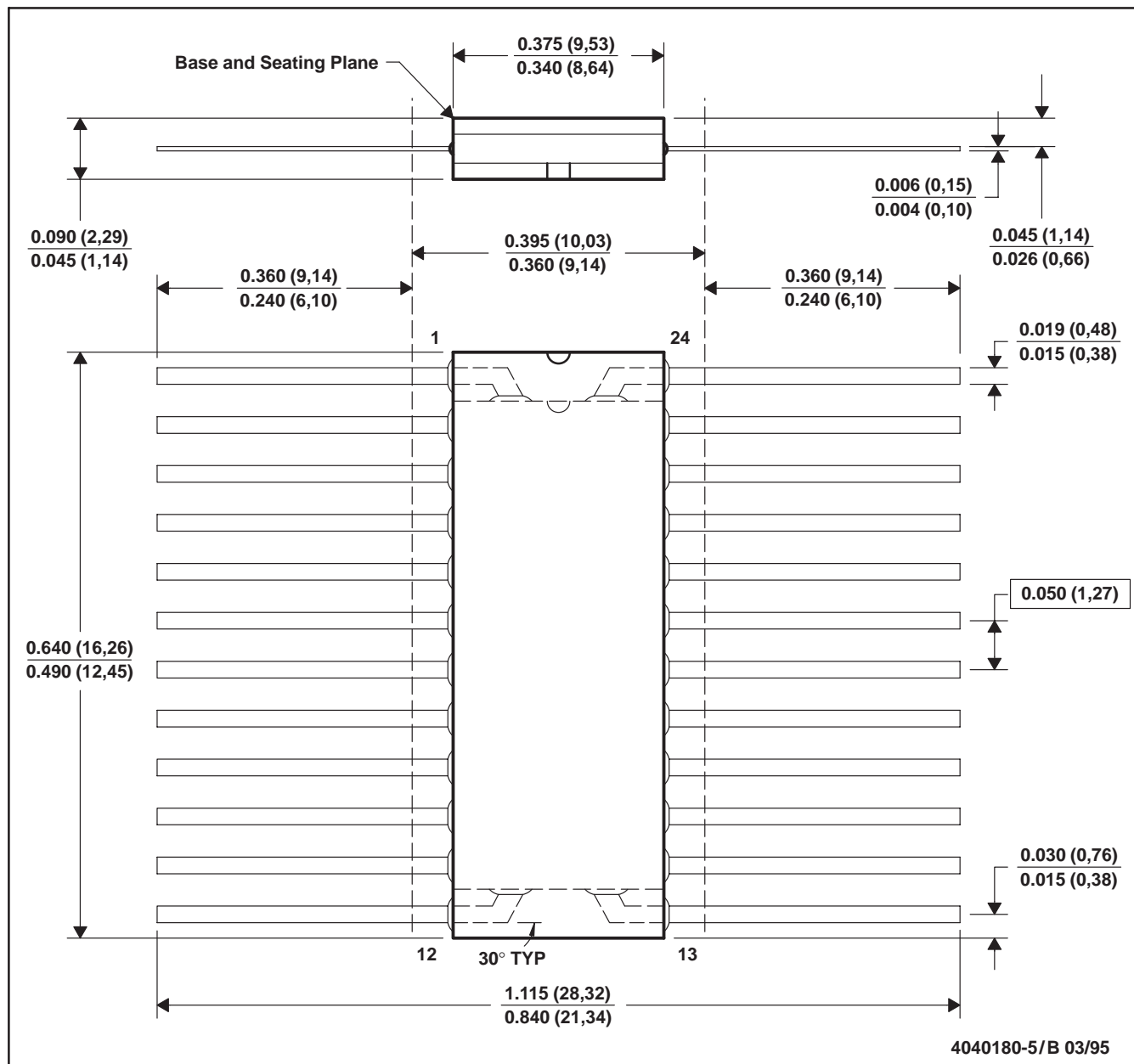
## CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

## W (R-GDFP-F24)

## CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - Index point is provided on cap for terminal identification only.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

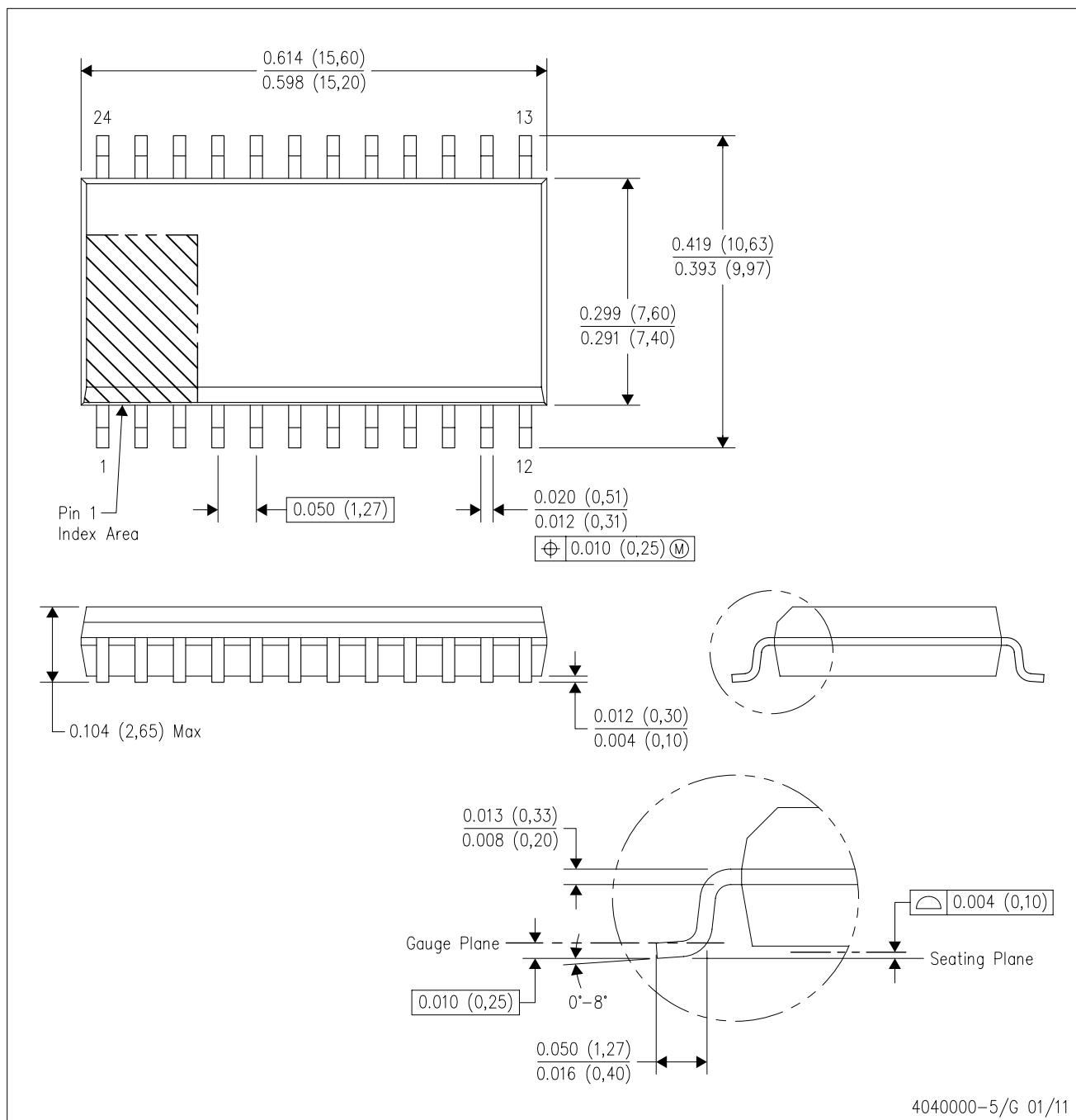
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G24)

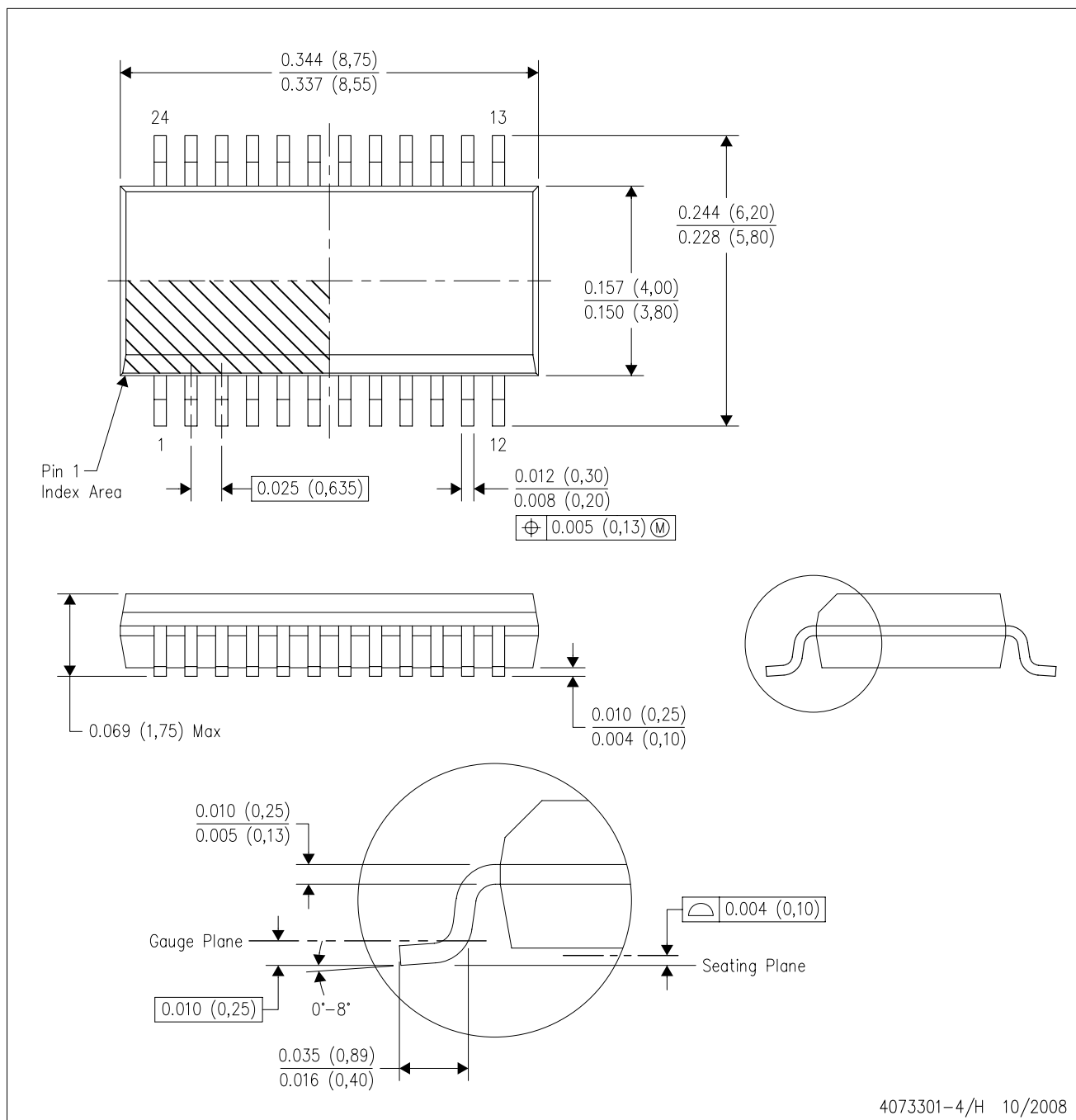
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

DBQ (R-PDSO-G24)

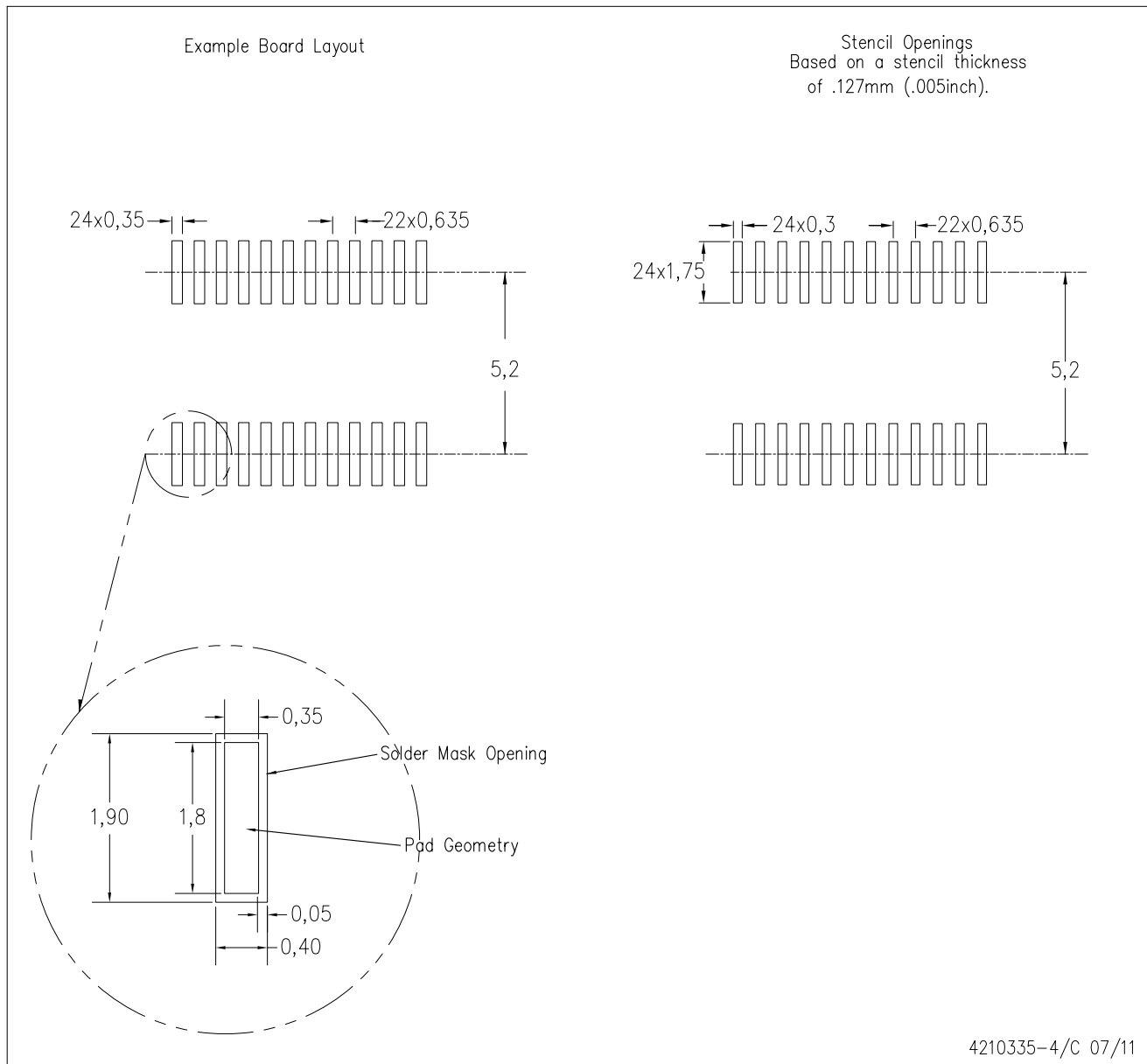
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

DBQ (R-PDSO-G24)

PLASTIC SMALL OUTLINE PACKAGE

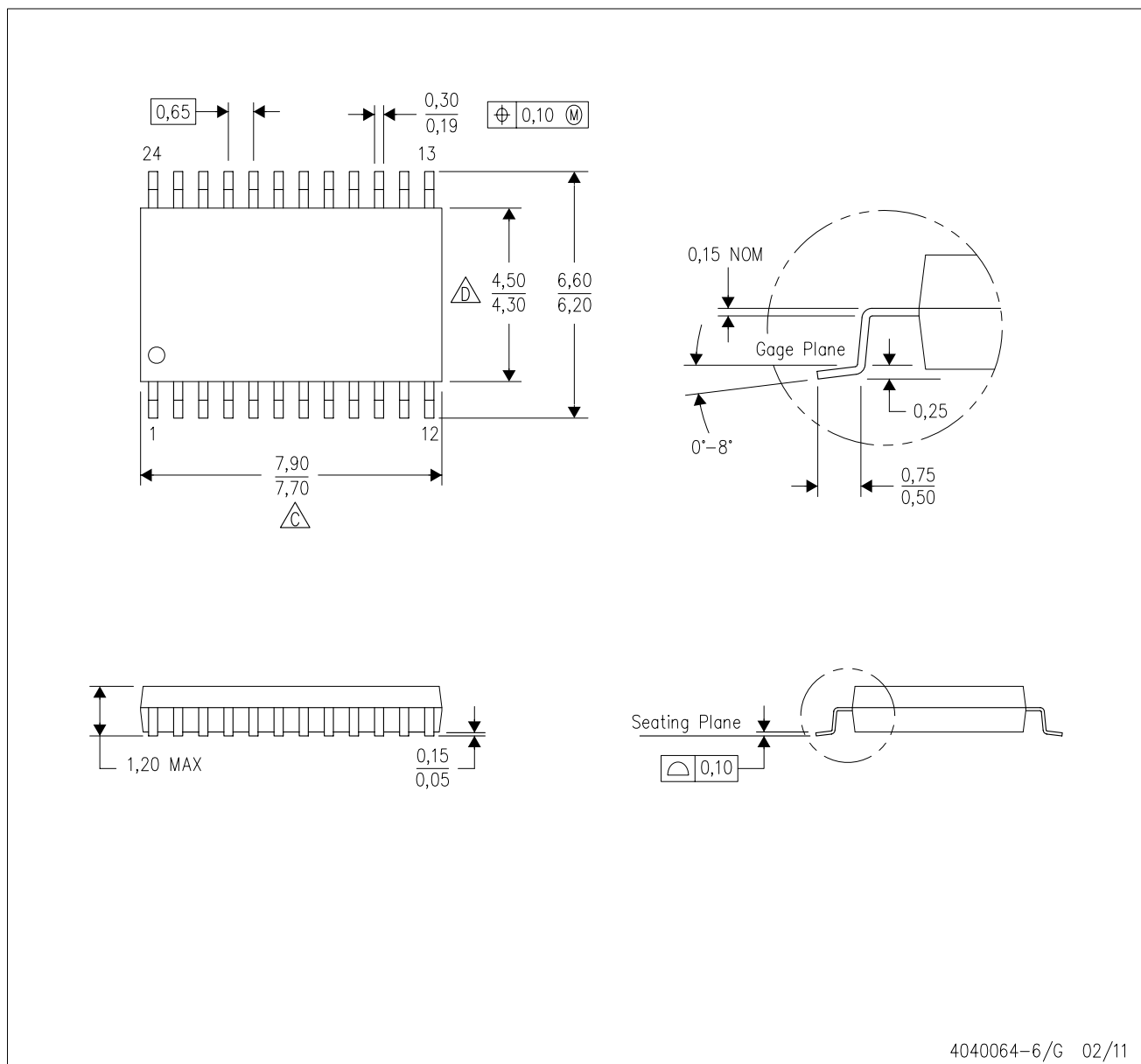


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

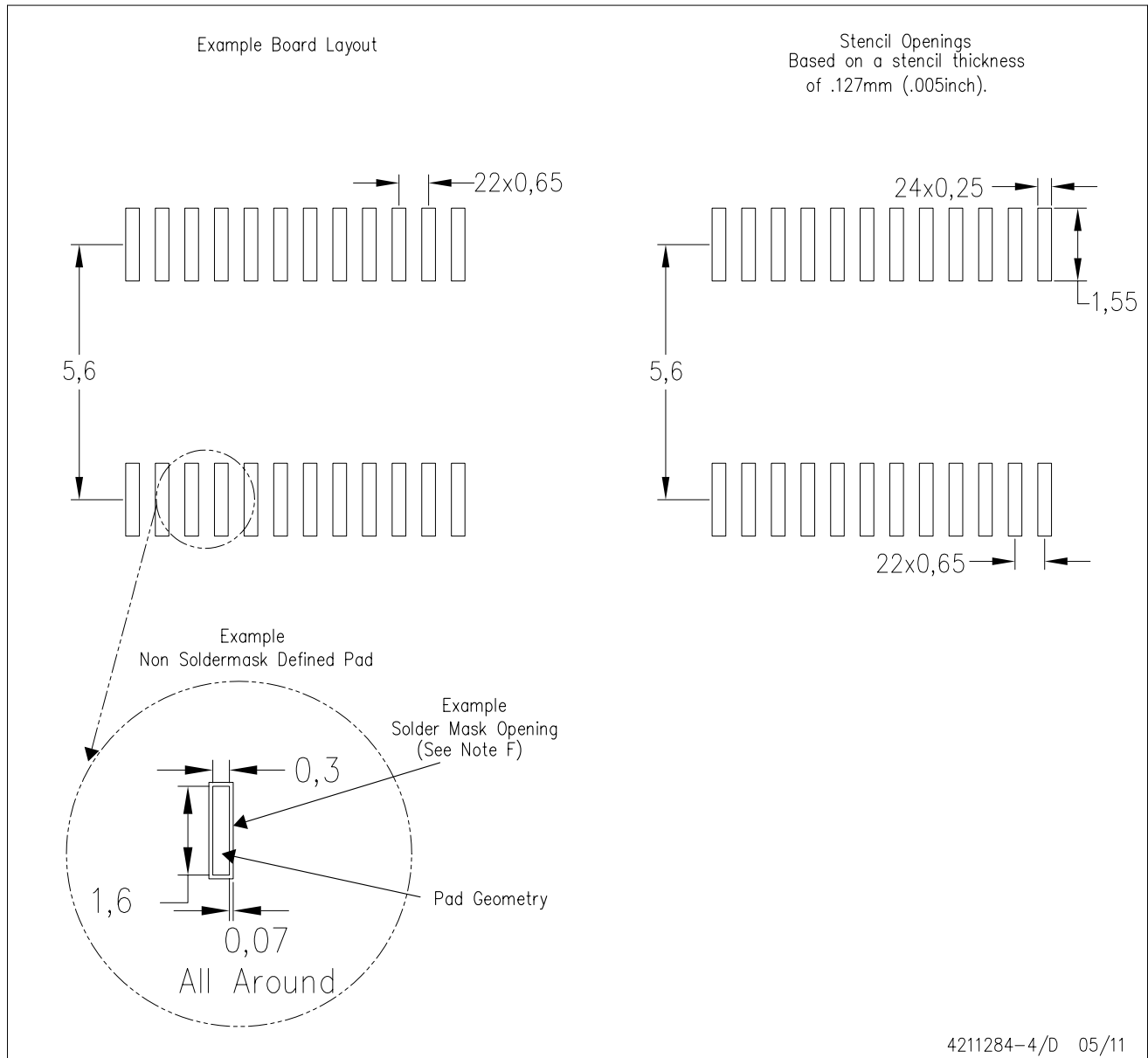


4040064-6/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## IMPORTANT NOTICE

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